



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-09-17
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	giovanni giacopello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
T2535T-8G-TR	7BD1*208SBM1	A	3068	2020-09-17
	Amount	UoM	Unit type	ST ECOPACK Grade
	1380	mg	Each	ECOPACK 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	245	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	-	



Package Designator	Size	Nbr of instances	Shape	
SIP	10.00,9.10,4.50	3	gull wing	
Comment	D2PAK CLIP			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.52	die - leadframe	374
Lead	6.04	soft solder	4377
Lead-Borate Glass	2.39	die	1735

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	6.04	Soft solder	4378
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	6.042	Soft solder	920195

Material Composition Declaration :							Mfr Item Name	7BD1*208SBM1					
note : Substance present with less 0.001mg will not be declared in this document													
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)	
Die	M-011 Other inorganic materials	13.979	mg	supplier	die	Silicon(Si)	7440-21-3		10.925	mg	781529	7915	
				supplier	metallisation	Gold(Au)	7440-57-5		0.056	mg	4006	41	
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.516	mg	36913	374	
				supplier	passivation	Silicon oxide	7631-86-9		0.088	mg	6295	64	
				JIG-R & California 65	glass	Lead-BorateGlass	65997-18-4	7c-I-Electrical and electronic	2.394	mg	171257	1735	
Leadframe	M-004 Copper and its alloys	900.741	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8		899.840	mg	999000	652058	
				supplier	alloy & coating	Copper Posphorous(CuP)	12517-41-8		0.901	mg	1000	653	
				SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	6.042	mg	920195	4378	
Soft solder	Solder	6.566	mg	supplier	solder	Silver(Ag)	7440-22-4		0.164	mg	24977	119	
				supplier	solder	Tin(Sn)	7440-31-5		0.327	mg	49802	237	
				supplier	solder	Flux residue	proprietary		0.033	mg	5026	24	
				supplier	solder	Silica vitreous	60676-86-0		312.222	mg	742001	226248	
Encapsulation	M-011 Other inorganic materials	420.784	mg	supplier	mold compound	Phenol resin	9003-35-4		21.039	mg	50000	15246	
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		46.286	mg	109999	33541	
				supplier	mold compound	other	proprietary		37.871	mg	90001	27443	
				supplier	mold compound	Carbon black	1333-86-4		3.366	mg	7999	2439	
				connections coating	Solder	6.314	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		6.314
Clip	M-004 Copper and its alloys	31.616	mg	supplier	alloy	Copper(Cu)	7440-50-8		31.616	mg	1000000	22910	